Amendments to the Abstract:

Please replace the original Abstract with the following new Abstract:

A method for reducing the impedance of a reference path in a printed circuit board includes forming a printed circuit board having a plurality of conductive layers including first, second, third, and fourth layers. The printed circuit board includes two or more vias interconnecting two or more of the conductive layers. A first via is part of a signal path configured to carry a signal from the first layer to the second layer. A second via is part of a reference path configured to carry said signal from a third layer to a fourth conductive layer. The method further includes embedding an electrical component, such as a capacitor, in the second via between two of the conductive layers.